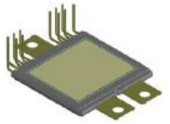
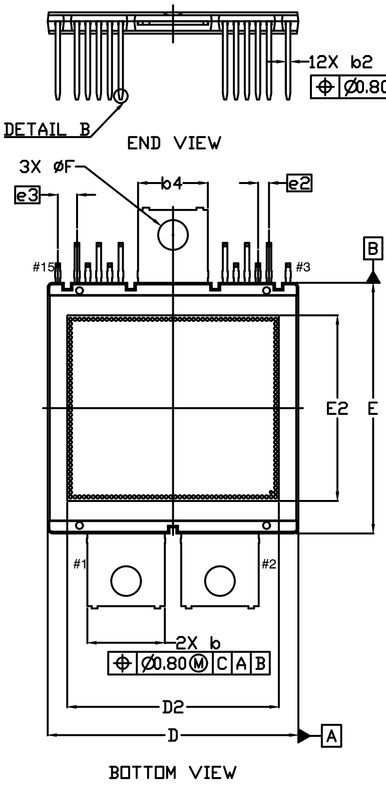


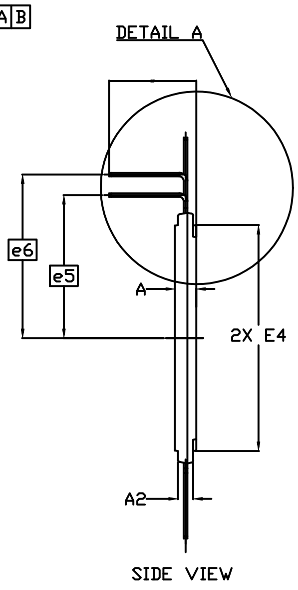
Gen II DSC AHPM15−CEC

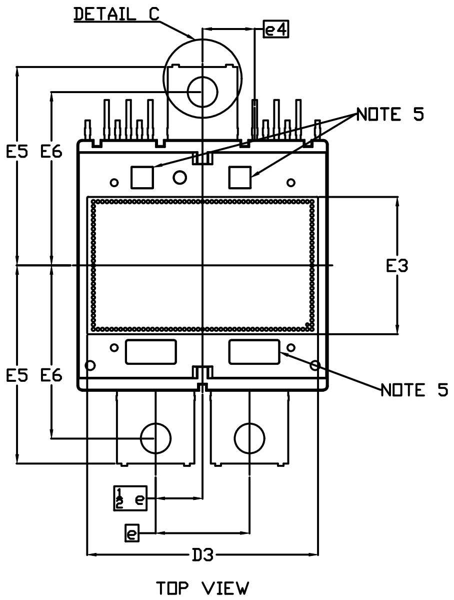
CASE MODHV
ISSUE O

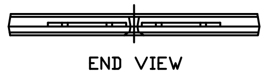
DATE 16 DEC 2021

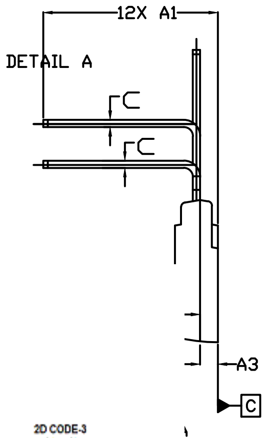
NOTES:
1. DIMENSIONING AND TOLERANCING PER. ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSIONS D & E DO NOT INCLUDE MOLD PROTRUSIONS
4. DIMENSIONS b & b2 DO NOT INCLUDE DAMBAR REMAIN.
5. MARKING AREA.





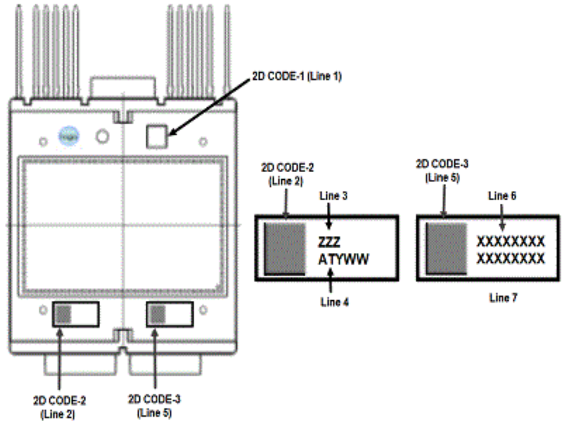






DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	4.65	4.70	4.75
A1	18.82	19.17	19.52
A2	3.20	3.40	3.60
A3	1.95 REF		
A4	2.75 REF		
b	16.90	17.00	17.10
b2	0.90	1.00	1.10
b3	0.50 REF		
b4	15.20	15.30	15.40
c	0.70	0.80	0.90
D	54.80	55.00	55.20
D2	45.80	46.80	47.80
D3	50.50	51.20	51.90
E	54.80	55.00	55.20

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
E2	40.20	41.20	42.20
E3	29.80	30.50	31.20
E4	49.40	49.60	49.80
E5	43.35	43.70	44.05
E6	37.70	38.00	38.30
e	20.60 BSC		
e2	2.40 BSC		
e3	4.20 BSC		
e4	11.45 BSC		
e5	31.40 BSC		
e6	35.90 BSC		
F	6.45	6.50	6.55
L	0.50 REF		
M	10° REF		



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DESCRIPTION:	**Gen II DSC AHPM15−CEC**	**PAGE 1 OF 2**

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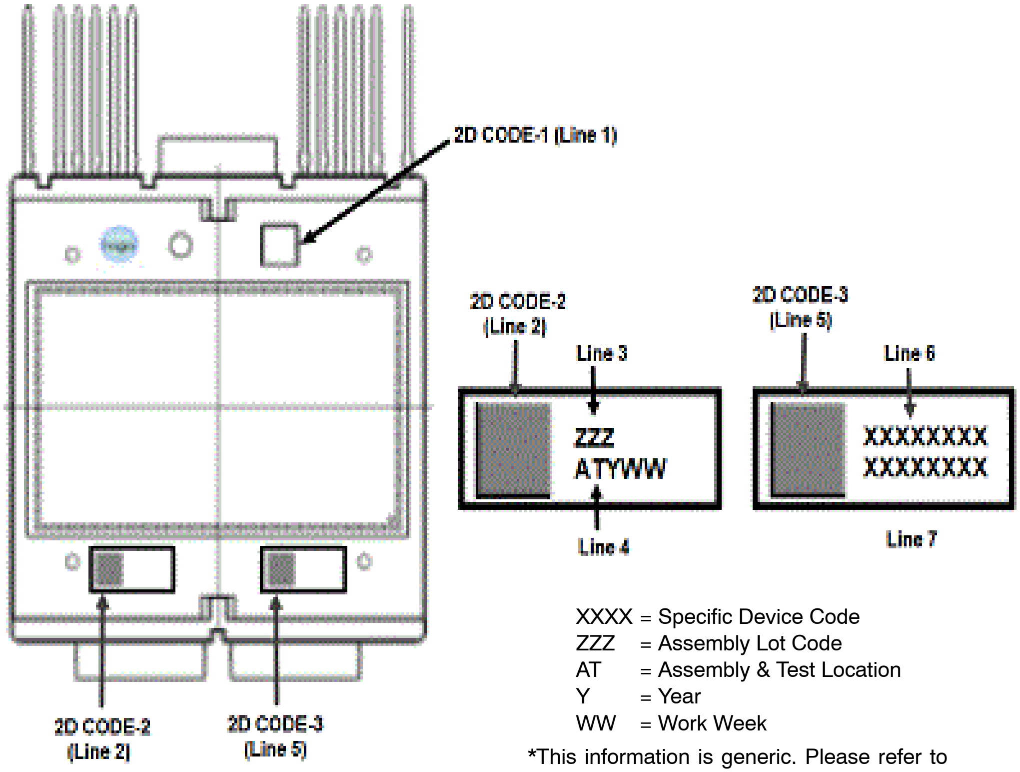
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

Gen II DSC AHPM15−CEC
CASE MODHV
ISSUE O

DATE 16 DEC 2021



XXXX = Specific Device Code
ZZZ = Assembly Lot Code
AT = Assembly & Test Location
Y = Year
WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

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